



# EGPL-G2N3

## M.2 to dual GbE LAN module

Customer:

Customer

Part Number:

Innodisk

Part Number:

Innodisk

Model Name:

Date:

|                                         |                                         |
|-----------------------------------------|-----------------------------------------|
| <div>Innodisk</div> <div>Approver</div> | <div>Customer</div> <div>Approver</div> |
|                                         |                                         |

Total Solution For  
Embedded Peripherals

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## REVISION HISTORY

| Revision | Description    | Date      |
|----------|----------------|-----------|
| 1.0      | First Released | May, 2021 |
|          |                |           |
|          |                |           |

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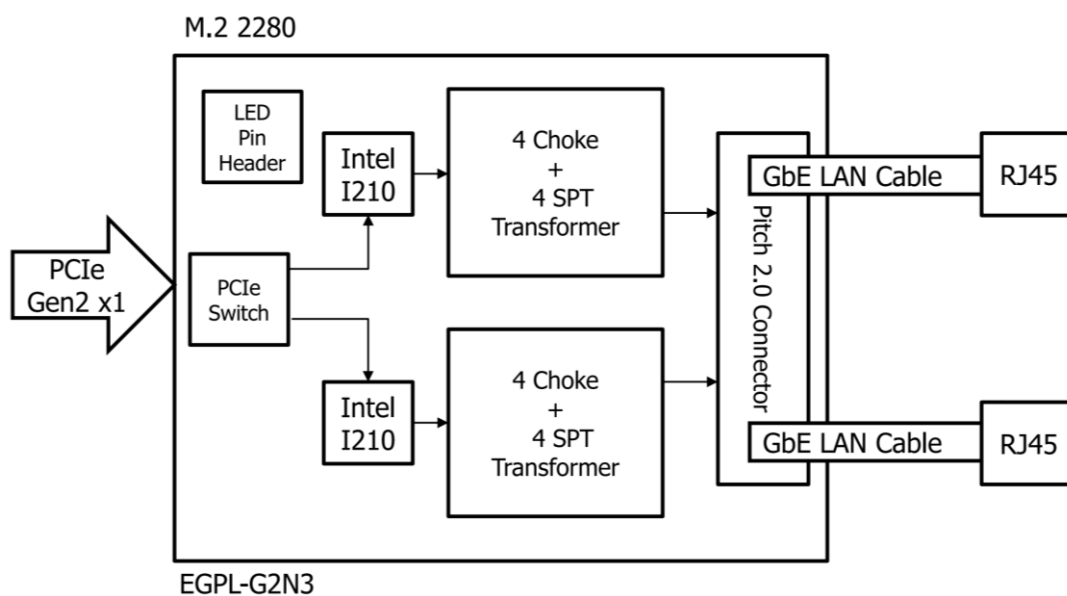
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# 1. Product Introduction

## 1.1. Overview

Innodisk EGPL-G2N3 is designed with standard M.2 2280 form factor, EGPL-G2N3 supports PCIe Gen 2.1 with a single lane to dual independent GbE LAN, optimized for higher performance and lower power. EGPL-G2N3 is designed with on-board transformer which brings you a flexible cable design for small form factor or embedded systems.



**Figure 1: Block Diagram**

## 1.2. Features

- Intel i210 chip. Dual GbE LAN ports
- Complies with EN61000-4-2 (ESD) Air-15kV, Contact-8kV
- Transformer on PCB for flexible cable design
- External LED indicator pin for speed 10/100/1000
- Optional Industrial Temperature (-40°C to +85°C) support
- 30μ" golden finger, 3-year warranty
- Industrial design, manufactured in innodisk Taiwan



**Figure 2: M.2 2280 Board Picture**



**Figure 3: 20pin Pitch 2.0 Connector to 2 RJ45 Cable**

## 2. Product Specifications

### 2.1. Device Parameters

**Table 1: Device Parameters**

|                          |                            |
|--------------------------|----------------------------|
| <b>Form Factor</b>       | M.2 2280 B-M Key           |
| <b>Input I/F</b>         | PCI Express 2.1 x 1        |
| <b>Output I/F</b>        | GbE LAN x 2                |
| <b>Output Connector</b>  | 20 Pin Pitch 2.0 Connector |
| <b>Dimension (WxLxH)</b> | M.2 Board: 22 x 80 x 9 mm  |

### 2.2. Electrical Specifications

#### 2.2.1. Power Requirement

**Table 2: Power Requirement**

| Item          | Connector         | Rating       |
|---------------|-------------------|--------------|
| Input voltage | M.2 Golden Finger | +3.3 DC +-5% |

#### 2.2.2. Power Consumption

**Table 3: Power Consumption**

| Voltage (V) | RMS (mA) | MAX (mA) |
|-------------|----------|----------|
| 3.3         | 601      | 635      |

### 2.3. Environmental Specifications

#### 2.3.1. Temperature Ranges

**Table 4: Temperature Ranges**

| Temperature | Range                                                           |
|-------------|-----------------------------------------------------------------|
| Operating   | Standard Grade: 0°C to +70°C<br>Industrial Grade: -40°C to +85° |
| Storage     | -55°C to +95°                                                   |



### 2.3.2. Humidity

Relative Humidity: 10-95%, non-condensing

### 2.3.3. Shock and Vibration

**Table 5: Shock and Vibration**

| Reliability      | Test Conditions                 | Reference Standards |
|------------------|---------------------------------|---------------------|
| Vibration        | 7 Hz to 2K Hz, 20G, 3 axes      | IEC 68-2-6          |
| Mechanical Shock | Duration: 0.5ms, 1500 G, 3 axes | IEC 68-2-27         |

### 2.3.4. Mean Time between Failure (MTBF)

Reliability prediction methodology provides the basis for reliability evaluation and analysis. The purpose of the prediction is to predict the life time of the product in units of failure rate and MTBF.

**Table 6: Mean Time between Failure (MTBF)**

| Product      | Condition                                                                                                                                                     | MTBF (Hours) |
|--------------|---------------------------------------------------------------------------------------------------------------------------------------------------------------|--------------|
| EGPL-G2N3-C1 | The analysis is at 25°C ambient temperature by Telcordia SR-332, Issues 4, Method I, Case 3 under Ground Benign, Controlled environment, 50% operation stress | 8,089,718    |
| EGPL-G2N3-W1 | The analysis is at 25°C ambient temperature by Telcordia SR-332, Issues 4, Method I, Case 3 under Ground Benign, Controlled environment, 50% operation stress | 8,384,395    |

### 2.4. CE and FCC Compatibility

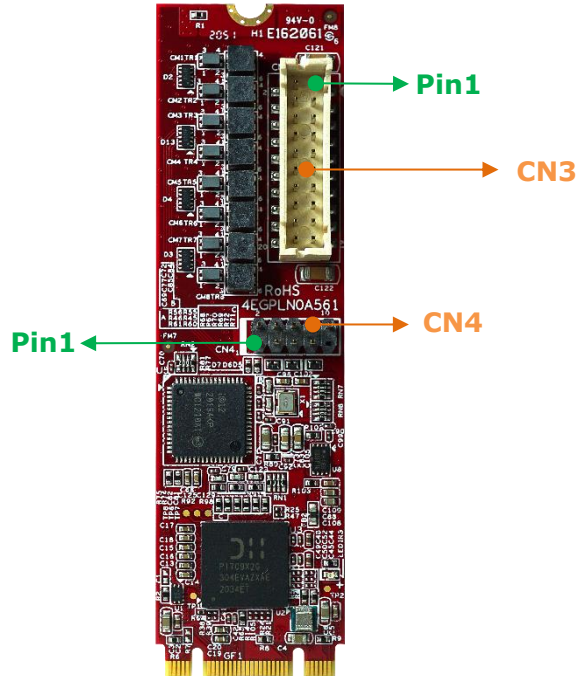
EGPL-G2N3 conforms to CE and FCC requirements.

### 2.5. RoHS Compliance

EGPL-G2N3 is fully compliant with RoHS directive.

## 2.6. Hardware

### 2.6.1. Layout



**Table 7: M.2 PCB Layout Legend**

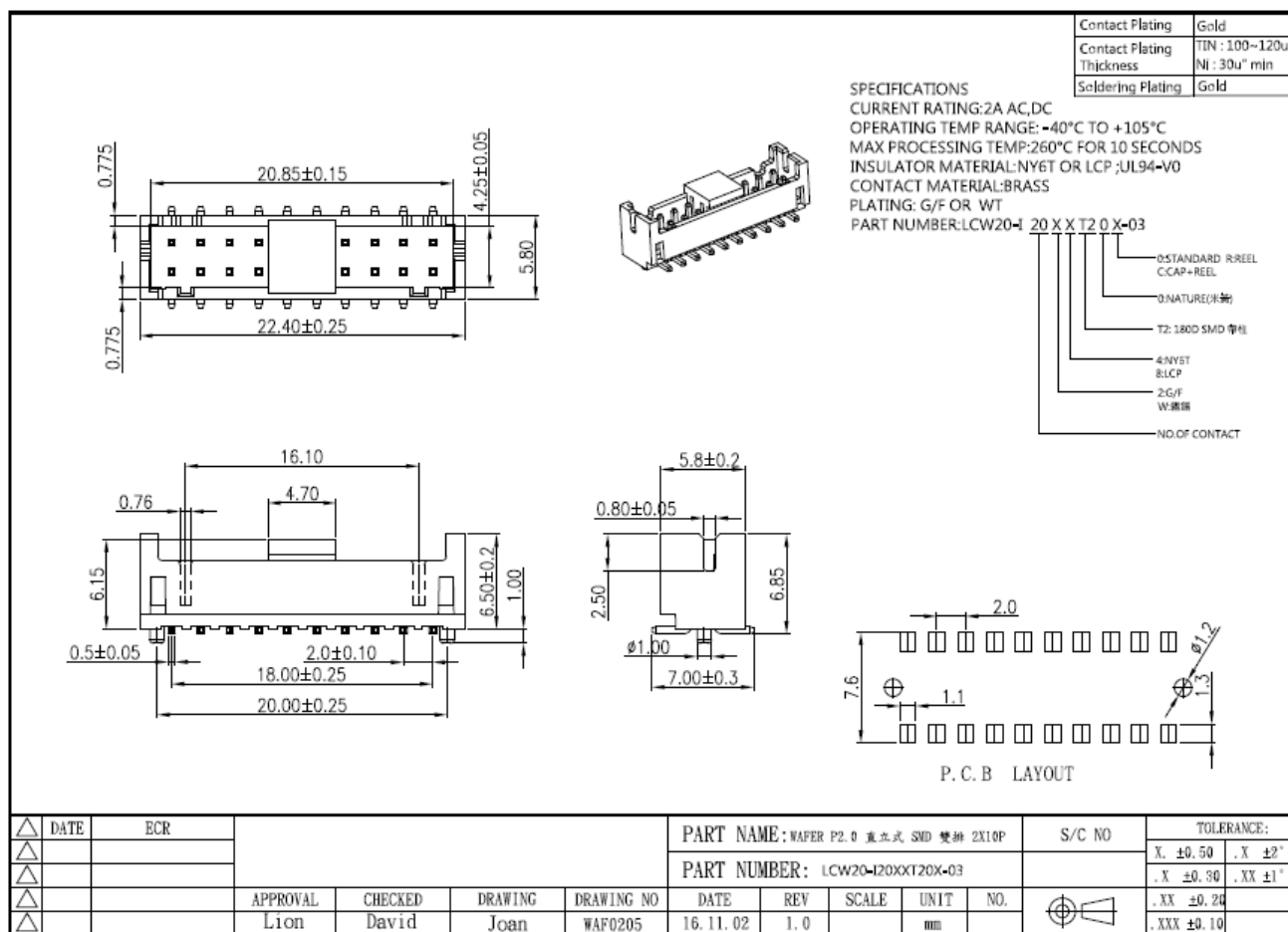
| Label      | Connector Type                                  | Function               |
|------------|-------------------------------------------------|------------------------|
| <b>CN3</b> | Wire to board SMD 2*10P 180°<br>P:2.0mm H:4.0mm | GbE LAN Signal         |
| <b>CN4</b> | 2x5 Pin Header (cut 9pin)<br>P:2.0mm            | 10/100/1000 LED Signal |

## 2.6.2. Pin Define

Table 8: M.2 Pin Define

| Signal Name         | Pin #     | Pin #     | Signal Name |
|---------------------|-----------|-----------|-------------|
|                     |           | <b>75</b> | GND         |
| 3.3V                | <b>74</b> | <b>73</b> | GND         |
| 3.3V                | <b>72</b> | <b>71</b> | GND         |
| 3.3V                | <b>70</b> | <b>69</b> | NC          |
| NC                  | <b>68</b> | <b>67</b> | NC          |
| <b>Module Key M</b> |           |           |             |
| NC                  | <b>58</b> |           |             |
| NC                  | <b>56</b> | <b>57</b> | GND         |
| PE_WAKE_N           | <b>54</b> | <b>55</b> | CLK+        |
| GND                 | <b>52</b> | <b>53</b> | CLK-        |
| PE_RST              | <b>50</b> | <b>51</b> | GND         |
| NC                  | <b>48</b> | <b>49</b> | RX+         |
| NC                  | <b>46</b> | <b>47</b> | RX-         |
| NC                  | <b>44</b> | <b>45</b> | GND         |
| SMBDATA             | <b>42</b> | <b>43</b> | TX+         |
| SMBCLK              | <b>40</b> | <b>41</b> | TX-         |
| NC                  | <b>38</b> | <b>39</b> | GND         |
| NC                  | <b>36</b> | <b>37</b> | NC          |
| NC                  | <b>34</b> | <b>35</b> | NC          |
| NC                  | <b>32</b> | <b>33</b> | GND         |
| NC                  | <b>30</b> | <b>31</b> | NC          |
| NC                  | <b>28</b> | <b>29</b> | NC          |
| NC                  | <b>26</b> | <b>27</b> | GND         |
| NC                  | <b>24</b> | <b>25</b> | NC          |
| NC                  | <b>22</b> | <b>23</b> | NC          |
| NC                  | <b>20</b> | <b>21</b> | GND         |
| <b>Module Key B</b> |           |           |             |
| NC                  | <b>10</b> | <b>11</b> | NC          |
| NC                  | <b>8</b>  | <b>9</b>  | NC          |
| NC                  | <b>6</b>  | <b>7</b>  | NC          |
| 3.3V                | <b>4</b>  | <b>5</b>  | NC          |
| 3.3V                | <b>2</b>  | <b>3</b>  | GND         |
|                     |           | <b>1</b>  | GND         |

### 2.6.3. I/O Connector Mechanical Drawing & Pin Defines



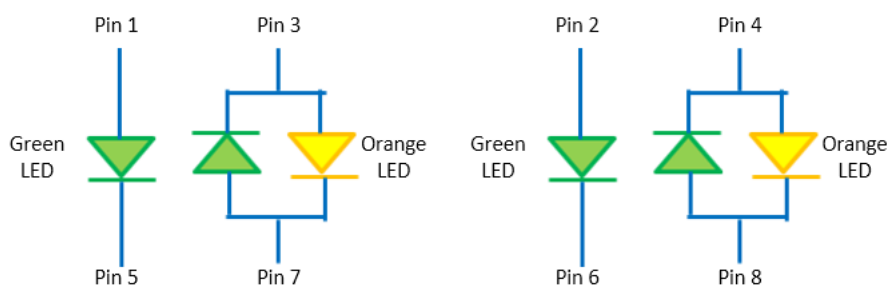
**Figure 4: Wire to Board SMD 2\*10P Connector Drawing**

**Table 9: Wire to Board SMD 2\*10P Connector (CN3) Pin Define**

| Signal Name | Pin # | Pin # | Signal Name |
|-------------|-------|-------|-------------|
| NC          | 2     | 1     | GND         |
| P1_MDI0P_CN | 4     | 3     | P1_MDI1P_CN |
| P1_MDI0N_CN | 6     | 5     | P1_MDI1N_CN |
| P1_MDI2P_CN | 8     | 7     | P1_MDI3P_CN |
| P1_MDI2N_CN | 10    | 9     | P1_MDI3N_CN |
| P2_MDI0P_CN | 12    | 11    | P2_MDI1P_CN |
| P2_MDI0N_CN | 14    | 13    | P2_MDI1N_CN |
| P2_MDI2P_CN | 16    | 15    | P2_MDI3P_CN |
| P2_MDI2N_CN | 18    | 17    | P2_MDI3N_CN |
| NC          | 20    | 19    | GND         |

**Table 10: 2X5 Pin Header (CN4) Pin Define**

| Signal Name      | Pin #    | Pin #     | Signal Name      |
|------------------|----------|-----------|------------------|
| 3.3V_LANB        | <b>1</b> | <b>2</b>  | 3.3_LANA         |
| LANB_LINK_100_N  | <b>3</b> | <b>4</b>  | LANA_LINK_100_N  |
| LANB_LINK_ACT_N  | <b>5</b> | <b>6</b>  | LANA_LINK_ACT_N  |
| LANB_LINK_1000_N | <b>7</b> | <b>8</b>  | LANA_LINK_1000_N |
|                  |          | <b>10</b> | GND              |

**Table 11: LAN LED Table**


| Speed       | Orange/Green (Status) | Green (Active/Link) |
|-------------|-----------------------|---------------------|
| <b>10M</b>  | OFF                   | Flash               |
| <b>100M</b> | ON (Green)            | Flash               |
| <b>1G</b>   | ON (Orange)           | Flash               |

### 2.6.4. EGPL-G2N3 Mechanical Drawing

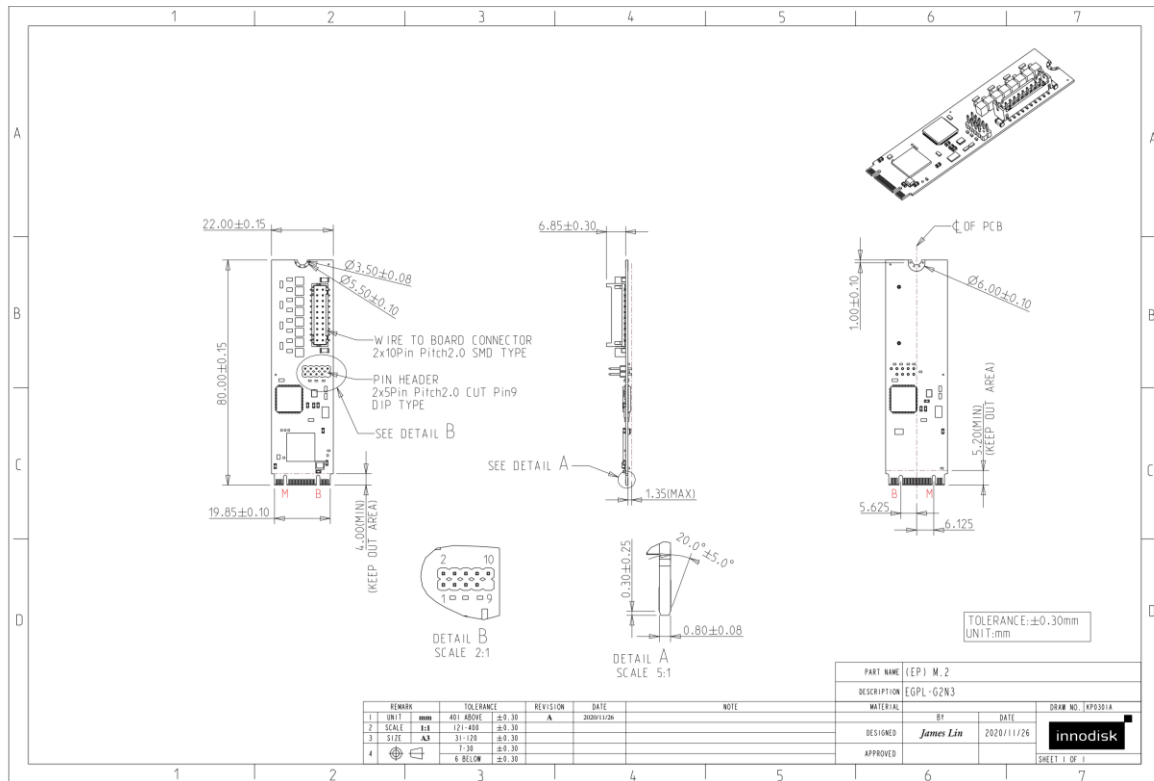


Figure 5: EGPL-G2N3 M.2 Board Drawing

### 2.6.5. Cable Mechanical Drawing

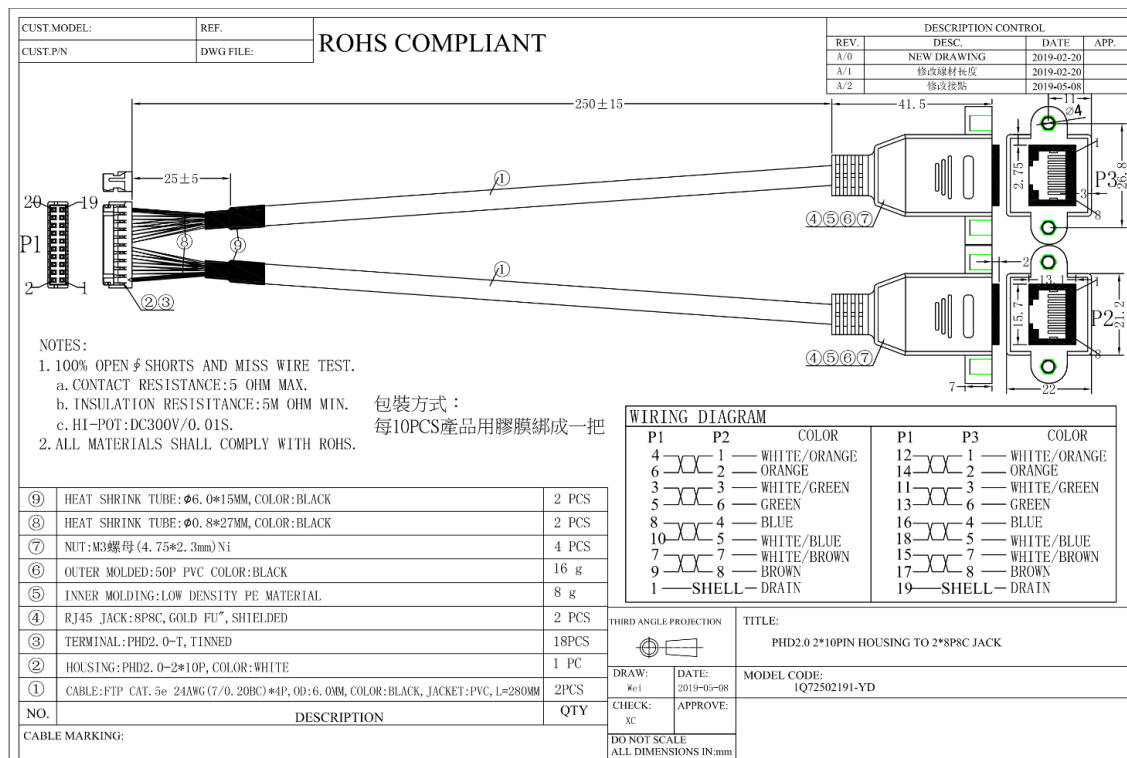


Figure 6: 20pin Pitch 2.0 Connector to 2 RJ45 Cable Drawing

#### **2.6.6. Packing List**

- EGPL-G2N3 M.2 2280 Board x 1
- 20pin Pitch 2.0 Connector to 2 RJ45 Cable x 1

#### **2.7. Software Support**

- Windows: XP(32bit), 7(32/64bit), 8/8.1(32/64 bit), 10(32/64bit)
- Linux: Kernel 2.4 above.

## **3. Installation Guide**

Please download driver from Myinnodisk web site.

<https://myinnodisk.innodisk.com/myinnodisk/Login.aspx>

Or you can download intel i210 chip driver from intel official web site directly.

<https://downloadcenter.intel.com/product/64399/Intel-Ethernet-Controller-I210-Series>

## 4. Appedix

innodisk

### 宜鼎國際股份有限公司 Innodisk Corporation

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Tel: (02) 7703-3000 Internet: <https://www.innodisk.com/>

#### RoHS 自我宣告書 (RoHS Declaration of Conformity)

**Manufacturer Products: All Innodisk EM FLASH, DRAM and EP products**

- 一、 宜鼎國際股份有限公司（以下稱本公司）特此保證售予貴公司之所有產品，皆符合歐盟 2011/65/EU 及 (EU) 2015/863 關於 RoHS 之規範要求。  
Innodisk Corporation declares that all products sold to the company, are complied with European Union RoHS Directive (2011/65/EU) and (EU) 2015/863 requirement.
- 二、 本公司同意因本保證書或與本保證書相關事宜有所爭議時，雙方宜友好協商，達成協議。  
Innodisk Corporation agrees that both parties shall settle any dispute arising from or in connection with this Declaration of Conformity by friendly negotiations.
- 三、 本公司聲明我們的產品符合 RoHS 指令的附件中 (7a)、(7c-I) 允許豁免。  
We declare, our products permitted by the following exemptions specified in the Annex of the RoHS directive.
  - ※ (7a) Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead).
  - ※ (7C-I) Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectric devices, or in a glass or ceramic matrix compound.

| Name of hazardous substance | Limited of RoHS ppm (mg/kg) |
|-----------------------------|-----------------------------|
| 鉛 (Pb)                      | < 1000 ppm                  |
| 汞 (Hg)                      | < 1000 ppm                  |
| 鎘 (Cd)                      | < 100 ppm                   |
| 六價鉻 (Cr 6+)                 | < 1000 ppm                  |
| 多溴聯苯 (PBBs)                 | < 1000 ppm                  |
| 多溴二苯醚 (PBDEs)               | < 1000 ppm                  |
| 鄰苯二甲酸二(2-乙基己基)酯 (DEHP)      | < 1000 ppm                  |
| 鄰苯二甲酸丁酯苯甲酯 (BBP)            | < 1000 ppm                  |
| 鄰苯二甲酸二丁酯 (DBP)              | < 1000 ppm                  |
| 鄰苯二甲酸二異丁酯 (DIBP)            | < 1000 ppm                  |

#### 立保證書人 (Guarantor)

Company name 公司名稱: Innodisk Corporation 宜鼎國際股份有限公司

Company Representative 公司代表人: Randy Chien 簡川勝

Company Representative Title 公司代表人職稱: Chairman 董事長

Date 日期: 2020 / 03 / 03





宜鼎國際股份有限公司  
Innodisk Corporation  
REACH Declaration

Tel:(02)7703-3000 Fax:(02) 7703-3555 Internet: <https://www.innodisk.com/>

Innodisk Corporation pursues its social responsibility for global environmental preservation by committing to be compliant with REACH regulation (REGULATION (EC) No 1907/2006). We hereby confirm that the product(s),

**Scope: Flash Memory, DRAM module and Embedded peripherals products.**

- The standard products of not listed in the **Appendix2** meet the requirements of REACH SVHC regulations(SVHCs < 0.1% in Article), as described in the candidate list table currently including 211 substances and shown on the ECHA website. (<http://echa.europa.eu/de/candidate-list-table>).
- Contain(s) one or more hazardous substances or constituents exceeding 0.1 % by weight in article if not otherwise specified in candidate list table.  
Where the threshold value is exceeded, the substances in question are to be declared in accompanying. (SVHCs > 0.1% in Article).
- Comply with REACH Annex XVII.

**Guarantor**

Company name 公司名稱： Innodisk Corporation 宜鼎國際股份有限公司

Company Representative 公司代表人： Yichuan Chen 陳怡全

Company Representative Title 公司代表人職稱： QA Manager 品保經理

Date 日期： 2021 / 03 / 03

# CERTIFICATE OF CONFORMITY



**Product** : M.2 2280 to dual GbE LAN module  
**Brand** : Innodisk  
**Test Model** : EGPL-G2N3  
**Series Model** : E%PL-G\*N#  
 %: Form factor: (2: 2.5"SSD, 3:DDR3 DIMM, D:Dongle,G:NGFF\_M.2,  
 H:mPCIe Half, L:PCIe Low profile, M:mPCIe, S:PCIe Standard, X:Multi,  
 Z:Others)  
 \*: Output items: (1:1Port, 2:2Ports, 3:3Ports, 4:4Ports, A~Z:TBD, X:Multi)  
 #: Series: ( 1~9,A~Z)  
**Applicant** : Innodisk Corporation  
**Report No.** : CEBDBO-WTW-P21020611

We, **Bureau Veritas Consumer Products Services (H.K.) Ltd., Taoyuan Branch**, declare that the equipment above has been tested in our facility and found compliance with the requirement limits of applicable standards, in accordance with the Directive 2014/30/EU. The test record, data evaluation and Equipment Under Test (EUT) configurations represented herein are true and accurate under the standards herein specified.

**EN 55032:2015 +A11:2020, Class B**

**EN 61000-3-2:2014 (Not applicable)**

**EN 61000-3-3:2013 (Not applicable)**

**EN 55035:2017 +A11:2020**

EN 61000-4-2:2009 / IEC 61000-4-2:2008 ED. 2.0

EN 61000-4-3:2006 +A1:2008 +A2:2010 / IEC 61000-4-3:2010 ED. 3.2

EN 61000-4-4:2012 / IEC 61000-4-4:2012 ED. 3.0

EN 61000-4-5:2014 +A1:2017 / IEC 61000-4-5:2014 +A1:2017 ED. 3.0

EN 61000-4-6:2014 +AC:2015 / IEC 61000-4-6:2013 ED. 4.0

EN 61000-4-8:2010 / IEC 61000-4-8:2009 ED. 2.0

EN 61000-4-11:2004 +A1:2017 / IEC 61000-4-11:2004 +A1:2017 ED. 2.0 (Not applicable)

Broadband impulse noise disturbances (Not applicable)

**NOTE:** The above EN/IEC basic standards are applied with latest version if customer has no special requirement.

*Jim Hsiang*

Jim Hsiang / Associate Technical Manager

Mar. 26, 2021

No. 47-2, 14th Ling, Chia Pau Vil., Lin Kou Dist., New Taipei City, Taiwan

Tel: 886-2-26052180 Fax: 886-2-26051924

<http://www.bureauveritas-adt.com> E-Mail: [service.adt@tw.bureauveritas.com](mailto:service.adt@tw.bureauveritas.com)





## TEST REPORT

### CERTIFICATE OF CONFORMITY

Standards: 47 CFR FCC Part 15, Subpart B, Class B

ANSI C63.4:2014

Report No.: FDBDBO-WTW-P21020611

Model No.: EGPL-G2N3

Series Model: E%PL-G\*N#

#: Form factor: (2: 2.5"SSD, 3:DDR3 DIMM, D:Dongle,G:NGFF\_M.2,  
H:mPCIe Half, L:PCIe Low profile, M:mPCIe, S:PCIe Standard, X:Multi,  
Z:Others)

\*: Output items: (1:1Port, 2:2Ports, 3:3Ports, 4:4Ports, A~Z:TBD, X:Multi)

#: Series: ( 1~9,A~Z)

Received Date: Feb. 25, 2021

Test Date: Feb. 26 to 27, 2021

Issued Date: Mar. 26, 2021

Applicant: Innodisk Corporation

Address: 5F., No. 237, Sec. 1, Datong Rd., Xizhi Dist., New Taipei City 22161, Taiwan

Issued By: Bureau Veritas Consumer Products Services (H.K.) Ltd., Taoyuan Branch Lin  
Kou Laboratories

Lab Address: No. 47-2, 14th Ling, Chia Pau Vil., Lin Kou Dist., New Taipei City, Taiwan

FCC Registration /

Designation Number: 418586 / TW1078

Approved by :

  
Jim Hsiang / Associate Technical Manager

Date: Jan. 21, 2021

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Prepared by : Albee Chu / Specialist

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Report No.: FDBDBO-WTW-P21020611

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Report Format Version: 7.0.1

# Contact us

## Headquarters (Taiwan)

5F., No. 237, Sec. 1, Datong Rd., Xizhi Dist., New Taipei City 221, Taiwan

Tel: +886-2-77033000

Email: sales@innodisk.com

## Branch Offices:

### USA

usasales@innodisk.com

+1-510-770-9421

### Europe

eusales@innodisk.com

+31-40-3045-400

### Japan

jpsales@innodisk.com

+81-3-6667-0161

### China

sales\_cn@innodisk.com

+86-755-2167-3689

**www.innodisk.com**

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